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P08/REV03



SHEET

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To the Director of the United States Patent and Trademark Office: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

-Yoshito ISEI and Tokumi HIRAI

2. Name and address of receiving party(ies):

Name: SUMITOMO MITSUBISHI SILICON

Internal Address: CORPORATION

Street Address: 2-1, Shibaura 1-chome, Minato-ku

Tokyo, Japan

City: State: ZIP:

Additional name(s) & address(es) attached? ☐ Yes ☒ No

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: June 11 & 16, 2004

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is: 11 & 16 JUNE 2004

A. Patent Application No.(s)

06/24/2004 SDENBOB1 00000031 10872524

02 FC:8021

40.00 DP

B. Patent No.(s)

10 872524

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: George A. Loud, Esquire

Internal Address: LORUSSO, LOUD & KELLY

Street Address: 3137 Mount Vernon Avenue

City: Alexandria State: VA ZIP: 22305

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account☐ Authorized to be charged to deposit account

8. Deposit account number:

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

George A. Loud

Name of Person Signing

Signature

22 June 2004

Date

Total number of pages including cover sheet, attachments, and document:

4

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PATENT

REEL: 015505 FRAME: 0266

ASSIGNMENT

WHEREAS, we, Yoshito ISEI and Tokumi HIRAI of, respectively, 5-33, Kitahama 4-chome, Chuo-ku, Osaka-shi, Osaka, Japan and 2-1, Shibaura 1-chome, Minato-ku, Tokyo, Japan have invented certain improvements in METHOD FOR MEASURING THICKNESS OF THIN FILM-LIKE MATERIAL DURING SURFACE POLISHING, AND SURFACE POLISHING METHOD AND SURFACE POLISHING APPARATUS set forth in an application for Patent of the United States; and

WHEREAS, SUMITOMO MITSUBISHI SILICON CORPORATION, 2-1, Shibaura 1-chome, Minato-ku, Tokyo, Japan, is desirous of acquiring an interest therein;

NOW THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, we, Yoshito ISEI and Tokumi HIRAI, by these presents do sell, assign and transfer unto said SUMITOMO MITSUBISHI SILICON CORPORATION, its successors, legal representatives, heirs and assigns, right, title and interest in said application executed on the 11&16 days of June, 2004, (and we hereby authorize our attorneys, authorized to prosecute said application, to here insert the filing date and serial number of said application, when known: Serial

No. ____ / _____, filed _____) to all Patents in the United States which may be granted on said application, to all divisions, continuations and continuations-in-part of said application, or reissues or extensions of said Patent, all applications for Patent and all Patent therefor, to be held and enjoyed by SUMITOMO MITSUBISHI SILICON CORPORATION, for its use and behoof and for its legal representatives, successors, heirs, and assigns, to the full end of the term for which said Patent are granted and any extensions thereof, as fully and entirely as the same would have been held by us had this assignment and sale not been made; and for the same consideration, we hereby covenant and agree that, at the time of execution and delivery of this instrument, we hold good and full right and lawful authority to sell and convey the application for Patent above mentioned in the manner herein set forth; and for the same consideration we hereby covenant and agree that we will, whenever counsel of SUMITOMO MITSUBISHI SILICON CORPORATION or the counsel of its successors, legal representatives, heirs or assigns, shall advise that any proceeding in connection with said application for Patent, or any proceeding in connection with Patent in the United States, including interference proceedings, is lawful and desirable, or that any division, continuation or continuation-in-part of any application for Patent, or any reissue or extension of any Patent to be obtained thereon, is lawful and desirable, sign all papers and documents, take all lawful oaths, and do all acts necessary or required to be done for the procurement, maintenance,

enforcement and defense of said Patent, without charge to us, our successors, legal representatives, heirs and assigns, but at the cost and expense of SUMITOMO MITSUBISHI SILICON CORPORATION, its successors, legal representatives, heirs and assigns; and we hereby request the Commissioner of Patents to issue said Patent to ourselves and to, SUMITOMO MITSUBISHI SILICON CORPORATION, as an assignee thereof.

<u>Yoshito Isei</u>	<u>16 JUNE 2004</u>
Yoshito ISEI	date

<u>Tokumi Hirai</u>	<u>11 JUNE 2004</u>
Tokumi HIRAI	date